


## Full Material Declaration for attached parts list

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	<b>Diotech Semiconductor AG</b> DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by: Udo Steinebrunner, Product Manager, -
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Declaration effective from: 2 January 2014 [Approved on 4 September 2019, 09:14 GMT]

## Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	11.50000%	Gold	7440-57-5	8.50000%
			ALUMINIUM	7429-90-5	12.00000%
			Silicon	7440-21-3	79.50000%
Die attach	Gold	3.50000%	Tin	7440-31-5	20.00000%
			Gold	7440-57-5	80.00000%
Encapsulation	EP (Epoxy resin)	47.20000%	Carbon black	1333-86-4	0.30000%
			ANTIMONY TRIOXIDE	1309-64-4	0.80000%
			3,3',5,5'-Tetrabromobisphenol A	79-94-7	0.99000%
			Epoxy resin 89	26335-32-0	27.61000%
			Quartz sand	60676-86-0	70.30000%
Inner preparation	Gold	1.50000%	Gold	7440-57-5	100.00000%
Leadfinish	Tin plating	5.30000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	31.00000%	Copper	7440-50-8	100.00000%

## Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOT-23/TO-236	Diode/Transistor SMD	0.01	g